Thursday March 28, 2024 12:30 p.m.

The 2023 Harvey Rosten Award

Sponsored by Siemens Digital Industries Software

For Outstanding Work in the Field of Thermal Analysis of Electronic Equipment:

Applicability of JESD51-14 to Clip-bonded, Discrete Power Devices

29th THERMINIC Workshop, Budapest, Hungary, September 2023

Szilárd Zsigmond Szőke

Henrik Sebők

Szilárd Zsigmond Szőke is working at the Engineering Center Budapest of Robert Bosch Kft. as senior expert for power electronics and thermal behaviour of electronic components. His team (ThID) performs thermal measurements and simulations of components, modules, and full automotive control units, focusing on matching models with reality. Szilárd received his Electrical Engineering diploma from the "Politechnica" University of Timisoara (Romania) in 2004, and worked there as teaching assistant, before joining Bosch in 2007. Since then, he was involved in development of start-stop and generator control units, blower controllers, and various actuators for automotive use. Szilárd has published 7 research papers and holds 4 patents.

Henrik Sebők graduated at Budapest University of Technology and Economics as mechanical engineer (2022 BS). He's been working at Engineering Center Budapest of Robert Bosch Kft. as thermal simulation engineer since 2019. His main interest is creating validated component models, ECU level simulations, as well as thermal measurements. So far, he involved in the publication of 1 research paper.

The Harvey Rosten Award

The Award is for outstanding work, recently published or in the public domain, which advances the analysis or modeling of thermal or thermomechanical effects in electronic equipment or components, including experiments aimed specifically at the validation of numerical models. The award is in the form of a plaque and a $1000 cash prize. The Award was established by the family and friends of Harvey Rosten, to commemorate his achievements in the field of thermal analysis of electronics equipment, and the thermal modeling of electronics parts and packages. The Award is made annually to encourage innovation and excellence in these and closely related fields.
The recipient is selected by the Selection Committee, made up of eminent practitioners in the electronics-thermal field. The criteria for selection are that the work: represents an advance in thermal analysis or thermal modeling of electronics equipment or components, including experiments aimed specifically at validating numerical models; demonstrates clear application to practical electronics design; demonstrates insight into the physical processes affecting the thermal behavior of electronics components, parts and systems; is innovative in embodying this understanding in either thermal analysis or thermal modeling; takes a pragmatic approach.